

## Parameter Limits

### Analysis Area / Beam

Technique	Smallest	Largest
TR-XRF	>10,000 $\mu$	15,000 $\mu$
GD-OES	>2,000 $\mu$	7,000 $\mu$
D-SIMS	>20 $\mu$	250 $\mu$
XPS	>15 $\mu$	500 $\mu$
LEXES	>5 $\mu$	200 $\mu$
EDX	>0.5 $\mu$	4 $\mu$
ToF-SIMS	>0.2 $\mu$	600 $\mu$
Auger	>0.015 $\mu$	100 $\mu$

Technique	Minimum Film Thickness	Depth of Information
TR-XRF	10 nm	1-3 nm
GD-OES	3 nm	0.1-0.3 nm
D-SIMS	20 nm	1-10 nm
XPS	5 nm	1-10 nm
LEXES	12 nm	700 nm
EDX	500 nm	500-3,000 nm
ToF-SIMS	0.2 nm	0.2 nm
Auger	5 nm	1-10 nm

Technique	Range of Elements	Quantitative Accuracy*
TR-XRF	S-U (16-92)	$\pm$ 1-20% (std)
GD-OES	H-U (1-92)	$\pm$ 0.4% (std)
D-SIMS	H-U (1-92)	$\pm$ 2% (std)
XPS	Li-U (3-92)	$\pm$ 10% (no)
LEXES	Be-U (4-92)	$\pm$ 5-10% (std)
EDX	B-U (5-92)	$\pm$ 10% (no)
ToF-SIMS	H-U (1-92)	$\pm$ 30% (std)
Auger	Li-U (3-92)	$\pm$ 30% (no)

\* with standards = std, standard not needed = no

## Detection Limits

